

WHAT IS CLAIMED IS:

1. A solid-state image pickup device comprising:
a solid-state image pickup element chip on which a
plurality of solid-state image pickup elements are
5 mounted; and

a protection cap provided on a light incident side
of said solid-state image pickup element chip and
adapted to protect said solid-state image pickup
element chip, characterized in that

10 said solid-state image pickup element chip is
formed on a substrate with a thermal expansion
coefficient equal to that of said protection cap, and
the substrate and said protection cap are sealed
with a sealing resin.

15 2. The device according to claim 1, characterized
in that said solid-state image pickup element chip is
adhered onto the substrate with a flexible adhesive.

20 3. The device according to claim 1, characterized
in that a contact preventive member is provided between
each one of the plurality of solid-state image pickup
elements and the sealing resin so the sealing resin
will not come into contact with each one of the
25 plurality of solid-state image pickup elements.

4. The device according to claim 1, characterized

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said solid-state image pickup element chip is formed on a substrate made of the same material as that of said protection cap, and

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the substrate and said protection cap are sealed
with a sealing resin.

8. The device according to claim 7, characterized
5 in that said solid-state image pickup element chip is
adhered onto the substrate with a flexible adhesive.

9. The device according to claim 7, characterized
in that a contact preventive member is provided between
10 each one of the plurality of solid-state image pickup
elements and the sealing resin so the sealing resin
will not come into contact with each one of the
plurality of solid-state image pickup elements.

10. The device according to claim 7,
15 characterized in that the substrate is one of a glass
substrate, ceramic substrate, metal substrate, and
resin substrate, or a substrate formed by stacking some
of the glass substrate, ceramic substrate, metal
20 substrate, and resin substrate.

11. The device according to claim 7,
characterized in that the sealing resin is a resin
selected from the group consisting of epoxy-, acrylic,
25 and phenol-based resins.

12. The device according to claim 7,

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characterized in that said solid-state image pickup
element chip is
formed on the substrate through a light-shielding layer
that shields light.

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